

Accompanying drawing(s) of the present invention: Method and apparatus for deposition removal and recycle cleaning of copper interconnect semiconductor process kits.

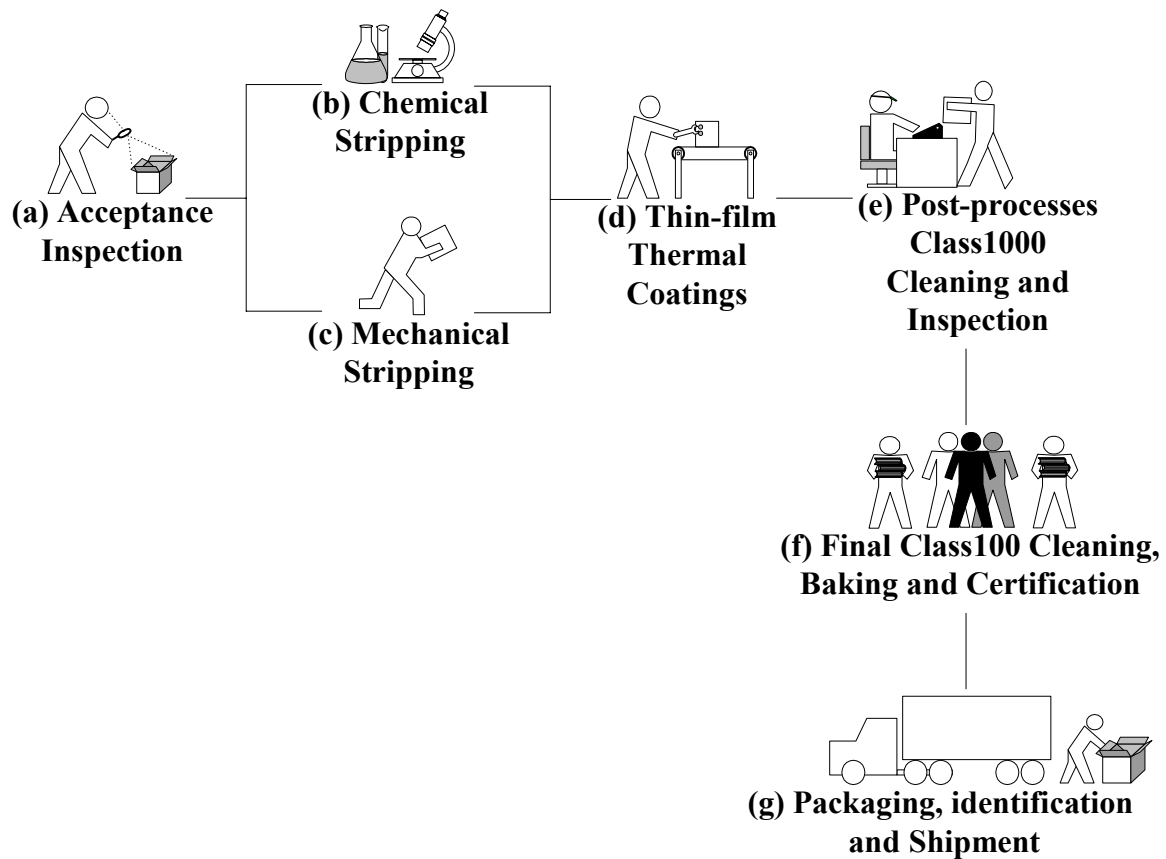


FIGURE 1 illustrates the flowchart for deposition removal and recycle cleaning of copper interconnect semiconductor process kits using chemical and mechanical processing in accordance with the present invention.

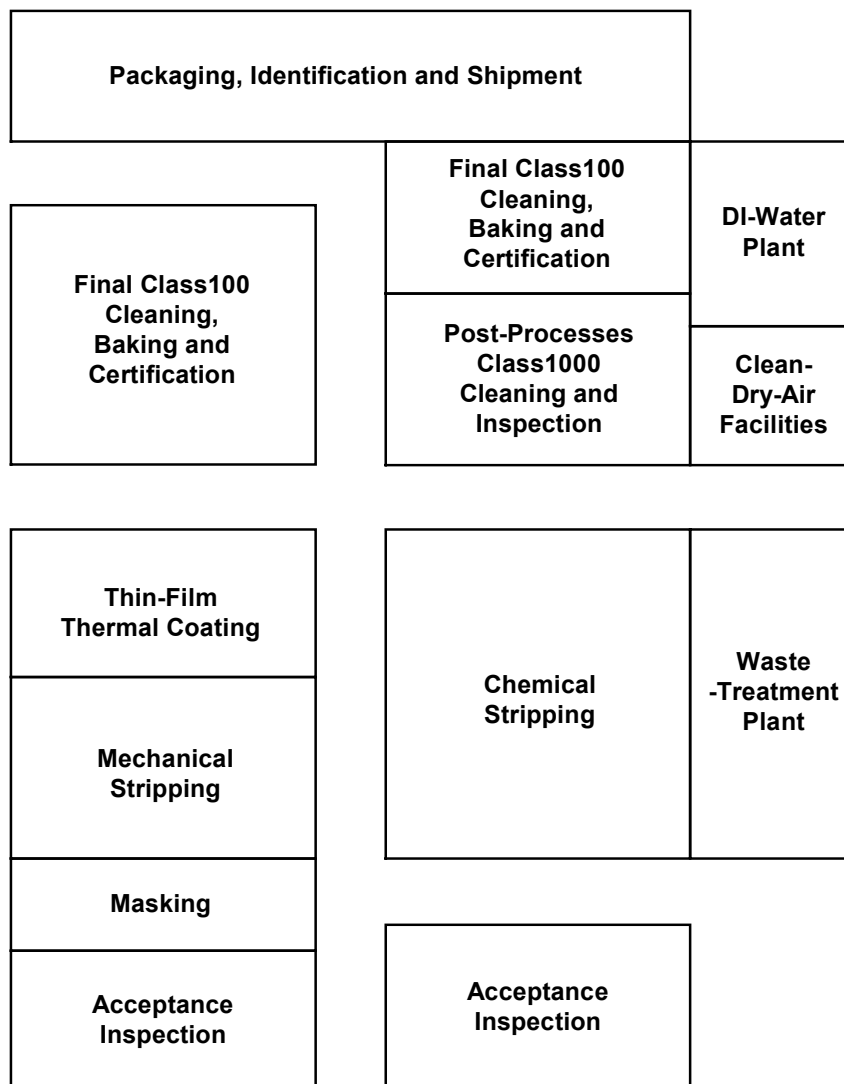


FIGURE 2 illustrates the layout of the apparatus for deposition removal and recycle cleaning of copper interconnect semiconductor process kits with the present invention.